# 500 mA / 13 V Adjustable CMOS LDO Regulator

## Description

The CAT6202 is a 13 V rated 500 mA CMOS low dropout regulator that provides fast response time to load current and line voltage changes in an automotive environment.

CAT6202 features a low R<sub>ON</sub> P-channel pass element with internal control circuitry which prevents reverse current flow should the voltage at  $V_{OUT}$  exceed  $V_{IN}$  as in the case of the car's battery voltage accidentally being applied to  $V_{OUT}$ .

Thermal protection and current limiting circuitry combine to protect the pass device against faults and abuse. Current limiting is user controlled through a single resistor to ground. A fault output ( $\overline{FLT}$ ) provides an alert should an over-current event or thermal shutdown occur.

CAT6202 comes on-line gracefully even though it may be driving heavy capacitive loads thanks to built-in soft-start circuitry. Its output is protected against accidental connection to voltages greater than  $V_{IN}$  and will not conduct current backwards into its supply.

CAT6202 is available in 8-pad 2 mm x 3 mm TDFN package.

## Features

- Guaranteed 500 mA Continuous Output Current
- Low Dropout Voltage of 250 mV Typical at 500 mA
- Input Voltage Range: 3.3 V to 13.5 V
- User Adjustable Output Voltage
- User Programmable Current Limit
- Fault Output to Indicate Under-voltage, Current Limiting or Thermal Shutdown has Occurred
- Fault Blanking: 3 ms
- V<sub>OUT</sub> Withstands Battery Fault Voltages of up to 14 V
- Soft-Start Prevents Current Surges
- Stable with Ceramic Output Capacitor
- ±1.0% Output Voltage Initial Accuracy
- ±2.0% Accuracy Over Temperature
- Thermal Protection
- 8 Pad TDFN Package
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



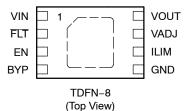
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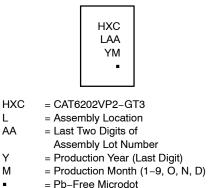


VP2 SUFFIX CASE 511AK





# MARKING DIAGRAMS



# **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

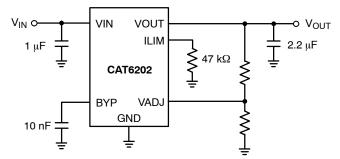


Figure 1. CAT6202 Typical Application

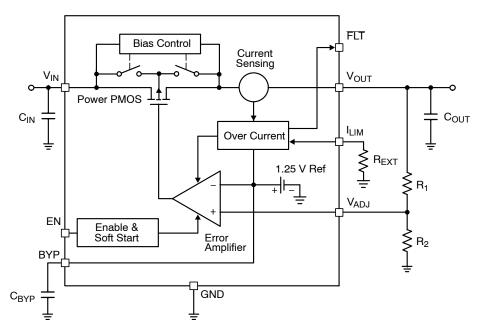


Figure 2. CAT6202 Functional Block Diagram

## **Table 1. PIN FUNCTION DESCRIPTION**

Pin No.	Pin Name	Description		
1	VIN	Supply voltage input		
2	FLT	Fault indicator (active low)		
3	EN	Enable input (active high)		
4	BYP	A capacitor between BYP and GND controls the regulator's turn-on speed and improves PSRR		
5	GND	Ground reference		
6	ILIM	Current limit control pin		
7	VADJ	Output voltage adjustment		
8	VOUT	LDO Output Voltage		

## **Table 2. ABSOLUTE MAXIMUM RATINGS**

Rating	Value	Unit
V <sub>IN</sub> , V <sub>OUT</sub>	0 to 16	V
All other pins	–0.3 to +6.0	V
Junction Temperature, T <sub>J</sub>	+150	°C
Power Dissipation, P <sub>D</sub>	Internally Limited (Note 1)	mW
Storage Temperature Range, T <sub>S</sub>	–65 to +150	°C
Lead Temperature (soldering, 5 sec.)	260	°C
ESD Rating (Human Body Model)	1000	V
ESD Rating (Machine Model)	350	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The maximum allowable power dissipation at any  $T_A$  (ambient temperature) is  $P_{Dmax} = (T_{Jmax} - T_A) / \theta_{JA}$ . Exceeding the maximum allowable power dissipation will result in excessive die temperature, and the regulator will go into thermal shutdown.

## Table 3. RECOMMENDED OPERATING CONDITIONS (Note 2)

Parameter	Range	Unit
V <sub>IN</sub> , V <sub>OUT</sub>	3.3 to 13.5	V
All other pins	0 to 6.0	V
Junction Temperature Range, T <sub>J</sub>	-40 to +125	°C
Package Thermal Resistance (SOIC), $\theta_{JA}$	235	°C/W
Package Thermal Resistance (TDFN), $\theta_{JA}$	92	°C/W

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.The device is not guaranteed to work outside its operating rating.

# **Pin Function**

**VIN** is the supply pin for both the LDO's operation and the load the LDO is driving. It is recommended that a 1  $\mu$ F ceramic bypass capacitor be placed between the V<sub>IN</sub> pin and ground in close proximity to the device. When using longer connections to the power supply, C<sub>IN</sub> value can be increased without limit. The operating input voltage range is from 3.3 V to 13 V.

**FLT** is an active low open-drain output indicating one of 3 fault conditions:

- 1. Input under-voltage:  $V_{IN}$  is below the intended output voltage
- 2. Over-current. Brief over-current events are masked by a 3 ms time delay. CAT6202 will limit current anytime the load tries to draw more than the maximum allowed however reporting of this event will occur only if the event lasts longer than the delay timer. Events terminating before the timer reaches its full count are ignored and the timer is reset.
- 3. Over-temperature shutdown has occurred.

**EN** is an active HIGH logic level input for switching the regulator's output between ON and OFF. A weak internal pull down assures that if EN pin is left open, the circuit is disabled.

**BYP** controls the soft–start feature for the regulator. When large capacitive loads are present at the regulator's output, enabling the regulator will produce large current surges on the  $V_{IN}$  supply line. To reduce these surges the regulator can be turned on gently by connecting a capacitor between the BYP pin and ground. The larger the capacitance value the more slowly  $V_{OUT}$  approaches its programmed value. The table below gives a list of common capacitor values and their resulting turn–on times. If the soft–start feature is not desired, this pin should be left floating.

Capacitance [nF]	t <sub>ON</sub> [ms]
0	0.2
10	1
100	10

**GND** is the ground reference for the LDO. The TDFN package center metal pad is internally connected to GND. If electrical contact is made with this pad, it should be to GND and/or the ground plane of the PCB. Connection to the ground plane enhances thermal conductivity drawing heat out of the package and into the surrounding PCB.

**ILIM** stands for Current Limit and is the control input for setting the point at which the current limit is invoked.  $I_{LIM}$ 

is defined as the current at which  $V_{OUT}$  is still within 80% of its nominal value and should not be confused with I<sub>SC</sub>, the short circuit current, measured at  $V_{OUT} = 0$  V, which is typically 100 mA greater than I<sub>LIM</sub>.

A resistor  $R_{EXT}$  placed between  $I_{LIM}$  and GND selects the trip current according to a formula:

$$I_{\text{LIMIT}} = I_{\text{LIMIT0}} + \frac{\text{Current\_Limit\_Factor(CLF)}}{\text{R}_{\text{EXT}}} \quad (\text{eq. 1})$$

 $I_{LIM0}$  is the built-in minimum current limit (typically 150 mA), and CLF is a numerical value (typical 30,000 Volts) which relates the allowable load current to a resistance value. The value of this resistor is determined by the following equation:

$$\mathsf{R}_{\mathsf{EXT}}(\Omega) = \frac{\mathsf{CLF}(\mathsf{V})}{\mathsf{I}_{\mathsf{LIM}}(\mathsf{A}) - \mathsf{I}_{\mathsf{LIM0}}(\mathsf{A})} \tag{eq. 2}$$

It is recommended that  $I_{LIM}$  be set with at least 50%, and preferably 60%, higher than the maximum intended continuous  $I_{OUT}$ .

Example: Set  $I_{LIMIT} = 800 \text{ mA}$ 

$$\mathsf{R}_{\mathsf{EXT}}(\Omega) = \frac{30,000 \text{ V}}{0.8 \text{ A} - 0.15 \text{ A}} = 47 \text{ K}\Omega \tag{eq. 3}$$

**VADJ** is the output voltage control pin. A resistor divider placed between VOUT and GND whose center point connects to VADJ sets the LDO regulator's output voltage. Typical VADJ value is 1.25 V. The current through the resistor divider can be anywhere between 10  $\mu$ A and 1 mA. The higher this current is, the lower the noise.

**VOUT** is the LDO regulator output. A small 2.2  $\mu$ F ceramic bypass capacitor is required between VOUT and ground. For better transient response, its value can be increased to 4.7  $\mu$ F. This capacitor should be located near the device.

$$V_{OUT} = V_{ADJ} \left( 1 + \frac{R_1}{R_2} \right)$$
 (eq. 4)

VOUT is protected against short circuits and over-temp operation by internal circuitry. In the event of an over-current, the LDO behaves like a current source, limiting current at the output. The maximum current allowed is set by  $R_{EXT}$ , the resistor between ILIM and GND. If the load attempts to draw more than the allowed current, VOUT and IOUT decrease together and thus limit the total power delivered.

VOUT is protected against the application of voltages greater than VIN. For example, in automotive applications, if CAT6202 is powering a remote load and damage occurs to a wiring harness shorting a powered line, Battery + for instance, to VOUT, CAT6202 will not be damaged by this higher voltage being applied to VOUT.

### Table 4. ELECTRICAL CHARACTERISTICS

 $(V_{IN} = V_{OUT} + 1 V, V_{EN} = High, I_{OUT} = 1 mA, C_{IN} = 1 \mu F, C_{OUT} = 2.2 \mu F, R_{EXT} = 47 k\Omega$ , ambient temperature of 25°C (over recommended operating conditions unless specified otherwise). **Bold numbers** apply for the entire junction temperature range.)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>IN</sub>	Input Voltage		3.3		13.5	V
V <sub>OUT</sub>	Output Voltage		V <sub>ADJ</sub>		12.5	
V <sub>ADJ</sub>	ADJ Voltage		1.238	1.250	1.262	V
I <sub>ADJ</sub>	ADJ Input Current		0.5		2.0	μA
TC <sub>OUT</sub>	Output Voltage Temp. Coefficient			40		ppm/°C
$V_{R-LINE}$	Line Regulation	V <sub>OUT</sub> + 1.0 < V <sub>IN</sub> < 13 V	-0.2	±0.1	+0.2	%/V
			-0.4		+0.4	
V <sub>R-LOAD</sub>	Load Regulation	I <sub>OUT</sub> = 1 mA to 500 mA		1	2.5	%
V <sub>DROP</sub>	Dropout Voltage (Note 3)	I <sub>OUT</sub> = 500 mA		250	350	mV
I <sub>GND</sub>	Ground Current	I <sub>OUT</sub> = 0 mA		100	150	μA
		I <sub>OUT</sub> = 500 mA		160	300	
I <sub>GND-SD</sub>	Shutdown Ground Current	V <sub>EN</sub> < 0.4 V			2	μA
PSRR	Power Supply Rejection Ratio	f = 1 kHz, C <sub>BYP</sub> = 10 nF		62		dB
		f = 20 kHz, C <sub>BYP</sub> = 10 nF		52		
T <sub>ON</sub>	Turn–On Time	C <sub>BYP</sub> = 10 nF		700		μs
I <sub>SC</sub>	Output short circuit current	V <sub>OUT</sub> < 0.8 V	700	800	1000	mA
I <sub>LIM</sub>	Output current limit	V <sub>OUT</sub> = 0.8 V <sub>OUT</sub> (1 mA)	600	650	800	mA
CLF	Current Limit Factor	V <sub>OUT</sub> < 0.8 V	24	30	36	KV
t <sub>FD</sub>	Fault Delay		1.5	3	6	ms
V <sub>IN-UVLO</sub>	Under voltage lockout threshold			3.1		V
ESR	R <sub>OUT</sub> equivalent series resistance		5		500	mΩ
ENABLE I	NPUT	•	•	•		
Viu	Logic High Level	V <sub>IN</sub> = 3.3 to 13 V	2			V

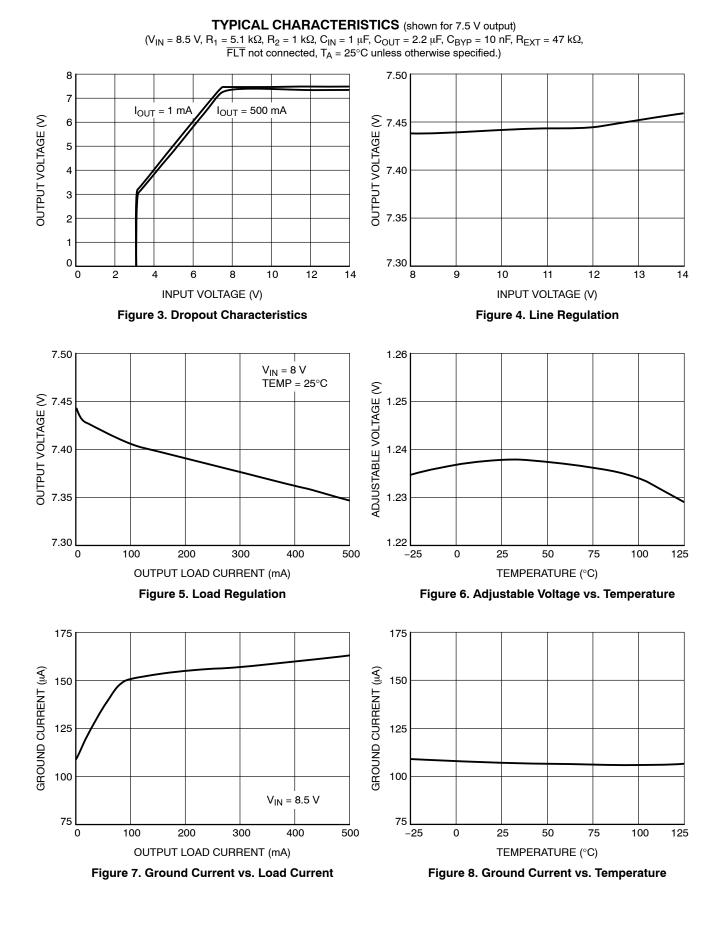
V <sub>HI</sub>	Logic High Level	V <sub>IN</sub> = 3.3 to 13 V	2			V
V <sub>LO</sub>	Logic Low Level	V <sub>IN</sub> = 3.3 to 13 V			0.4	V
I <sub>EN</sub>	Enable Input Current	V <sub>EN</sub> = 0.4 V		0.15	1	μΑ
		$V_{EN} = V_{IN}$		3	5	

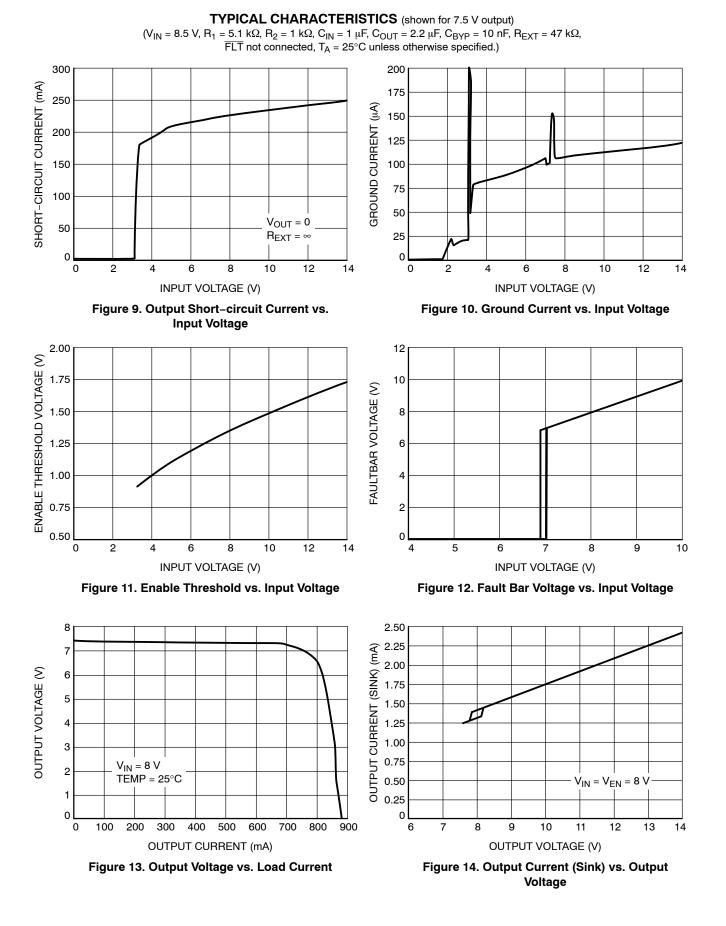
#### THERMAL PROTECTION

T <sub>SD</sub>	Thermal Shutdown		140	°C
T <sub>HYS</sub>	Thermal Hysteresis		10	°C

3. Dropout voltage is defined as the input-to-output differential at which the output voltage drops 2% below its nominal value. During test, the input voltage stays always above the minimum 3.3 V. The given values are for V<sub>OUT</sub> = 7.5 V. Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product

performance may not be indicated by the Electrical Characteristics if operated under different conditions.





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#### TYPICAL CHARACTERISTICS (shown for 7.5 V output) $(V_{IN} = 8.5 \ V, \ R_1 = 5.1 \ k\Omega, \ R_2 = 1 \ k\Omega, \ C_{IN} = 1 \ \mu F, \ C_{OUT} = 2.2 \ \mu F, \ C_{BYP} = 10 \ nF, \ R_{EXT} = 47 \ k\Omega,$ T<sub>A</sub> = 25°C unless otherwise specified. All transient characteristics are generated using the evaluation board CAT6202EVAL1.) 21-Sep-11 15:46:07 21-Sep-11 15:54:13 d-.1 ms 2.00 V .1 ms 2.00 V k 2 .1 ms 2.00 V .1 ms 2.00 V ----.... ----... .... .... ....

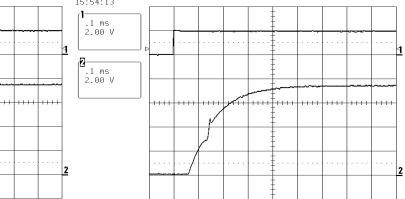


Figure 15. Enable Turn-On (No Load)

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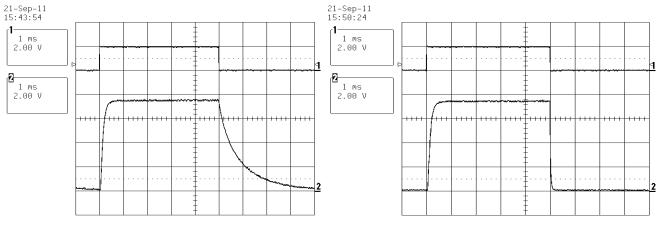
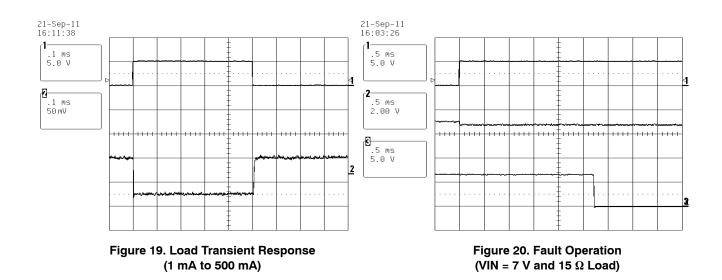


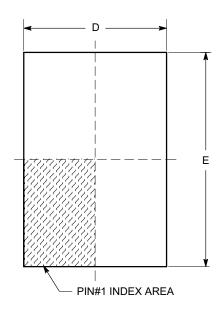
Figure 17. Enable Operation (No Load)

Figure 18. Enable Operation (15  $\Omega$  Load)

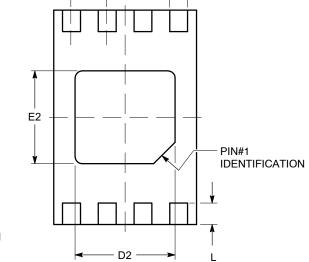


# PACKAGE DIMENSIONS

TDFN8, 2x3 CASE 511AK-01 ISSUE A







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TOP VIEW

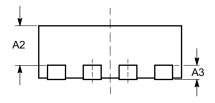
SIDE VIEW

SYMBOL	MIN	NOM	MAX		
А	0.70	0.75	0.80		
A1	0.00	0.02	0.05		
A2	0.45	0.55	0.65		
A3	0.20 REF				
b	0.20	0.25	0.30		
D	1.90	2.00	2.10		
D2	1.30	1.40	1.50		
E	2.90	3.00	3.10		
E2	1.20	1.30	1.40		
e	0.50 TYP				
L 0.20 0		0.30	0.40		

Notes:

All dimensions are in millimeters.
Complies with JEDEC MO-229.

**BOTTOM VIEW** 



FRONT VIEW

#### **Table 5. ORDERING INFORMATION**

Device Order Number	Specific Device Marking	Package Type	Lead Finish	$\mathbf{Shipping}^{\dagger}$
CAT6202VP2-GT3	HXC	TDFN-8	NiPdAu	Tape & Reel, 3,000 Units / Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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